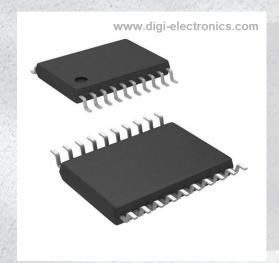


MC74ACT373DTR2G Datasheet



https://www.DiGi-Electronics.com

DiGi Electronics Part Number MC74ACT373DTR2G-DG

Manufacturer onsemi

Manufacturer Product Number MC74ACT373DTR2G

Description IC D-TYPE TRANSP SGL 8:8 20TSSOP

Detailed Description D-Type Transparent Latch 1 Channel 8:8 IC Tri-Stat

e 20-TSSOP



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.



Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
MC74ACT373DTR2G	onsemi
Series:	Product Status:
74ACT	Active
Logic Type:	Circuit:
D-Type Transparent Latch	8:8
Output Type:	Voltage - Supply:
Tri-State	4.5V ~ 5.5V
Independent Circuits:	Delay Time - Propagation:
1	8.5ns
Current - Output High, Low:	Operating Temperature:
24mA, 24mA	-40°C ~ 85°C (TA)
Grade:	Qualification:
Mounting Type:	Package / Case:
Surface Mount	20-TSSOP (0.173", 4.40mm Width)
Supplier Device Package:	Base Product Number:
20-TSSOP	74ACT373

Environmental & Export classification

8542.39.0001

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	



Octal Transparent Latch with 3-State Outputs

MC74AC373, MC74ACT373

The MC74AC373/74ACT373 consists of eight latches with 3–state outputs for bus organized system applications. The flip–flops appear transparent to the data when Latch Enable (LE) is HIGH. When LE is LOW, the data that meets the setup time is latched. Data appears on the bus when the Output Enable (\overline{OE}) is LOW. When \overline{OE} is HIGH, the bus output is in the high impedance state.

Features

- Eight Latches in a Single Package
- 3-State Outputs for Bus Interfacing
- Outputs Source/Sink 24 mA
- 'ACT373 Has TTL Compatible Inputs
- These are Pb-Free Devices

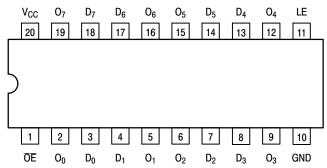


Figure 1. Pinout: 20-Lead Packages Conductors
(Top View)

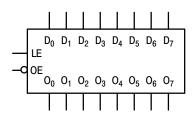


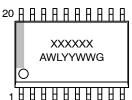
Figure 2. Logic Symbol

PIN ASSIGNMENT

PIN	FUNCTION
D ₀ -D ₇	Data Inputs
LE	Latch Enable Input
ŌĒ	Output Enable Input
O ₀ -O ₇	3-State Latch Outputs

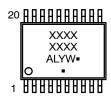
MARKING DIAGRAMS







TSSOP-20 DT SUFFIX CASE 948E



XXXXXX = Specific Device Code A = Assembly Location

WL, L = Wafer Lot YY, Y = Year WW, W = Work Week G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.

TRUTH TABLE

Inputs			Outputs
ŌĒ	LE	D _n	On
Н	Х	Χ	Z
L	Н	L	L
L	Н	Н	Н
L	L	X	O_0

H = HIGH Voltage Level

L = LOW Voltage Level

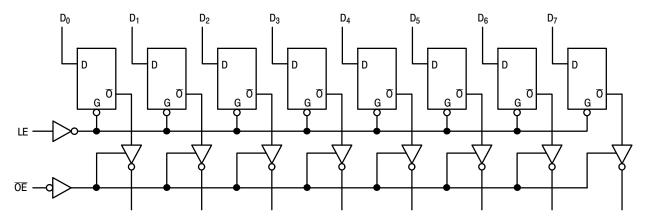
Z = High Impedance

X = Immaterial

O₀ = Previous O₀ before LOW-to-HIGH Transition of Clock

FUNCTIONAL DESCRIPTION

The MC74AC373/74ACT373 contains eight D-type latches with 3-state standard outputs. When the Latch Enable (LE) input is HIGH, data on the D_n inputs enters the latches. In this condition the latches are transparent, i.e., a latch output will change state each time its D input changes. When LE is LOW, the latches store the information that was present on the D inputs a setup time preceding the HIGH-to-LOW transition of LE. The 3-state standard outputs are controlled by the Output Enable ($\overline{\rm OE}$) input. When $\overline{\rm OE}$ is LOW, the standard outputs are in the 2-state mode. When $\overline{\rm OE}$ is HIGH, the standard outputs are in the high impedance mode but this does not interfere with entering new data into the latches.



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MAXIMUM RATINGS

Symbol	Paramet	er	Value	Unit
V _{CC}	DC Supply Voltage (Referenced to GND)	-0.5 to +6.5	V	
V _{IN}	DC Input Voltage (Referenced to GND)	-0.5 to V _{CC} +0.5	V	
V _{OUT}	DC Output Voltage (Referenced to GND) (No	ote 1)	-0.5 to V _{CC} +0.5	V
I _{IK}	DC Input Diode Current		±20	mA
I _{OK}	DC Output Diode Current		±50	mA
I _{OUT}	DC Output Sink/Source Current		±50	mA
I _{CC}	DC Supply Current, per Output Pin		±50	mA
I _{GND}	DC Ground Current, per Output Pin	±100	mA	
T _{STG}	Storage Temperature Range	-65 to +150	°C	
T_L	Lead temperature, 1 mm from Case for 10 Se	econds	260	°C
TJ	Junction Temperature Under Bias		140	°C
θЈА	Thermal Resistance (Note 2)	SOIC TSSOP	96 150	°C/W
MSL	Moisture Sensitivity	SOIC TSSOP	Level 3 Level 1	
F _R	Flammability Rating	Oxygen Index: 30% - 35%	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage	> 2000 > 1000	V	
I _{Latchup}	Latchup Performance Above	V _{CC} and Below GND at 85°C (Note 5)	±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- IouT absolute maximum rating must be observed.
- The package thermal impedance is calculated in accordance with JESD 51-7.
- 3. Tested to EIA/JESD22-A114-A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Тур	Max	Unit	
V			2.0	5.0	6.0	V
V _{CC}	Supply Voltage	'ACT	4.5	5.0	5.5	V
V _{IN} , V _{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	_	V _{CC}	V
		V _{CC} @ 3.0 V	_	150	-	
t _r , t _f	Input Rise and Fall Time (Note 6) 'AC Devices except Schmitt Inputs	V _{CC} @ 4.5 V	_	40	-	ns/V
	The Borlood Groupt Collinia Impaid	V _{CC} @ 5.5 V	_	25	-	
	Input Rise and Fall Time (Note 7)	V _{CC} @ 4.5 V	_	10	-	no \ /
t _r , t _f	'ACT Devices except Schmitt Inputs	_	8.0	_	ns/V	
T _A	Operating Ambient Temperature Range	-40	25	85	°C	
loh	Output Current – High	_	_	-24	mA	
I _{OL}	Output Current – Low	_	_	24	mA	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

6. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.

- 7. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

			74	AC	74AC		
Symbol	Parameter	V _{CC} (V)	T _A = 4	+25°C	T _A = -40°C to +85°C	Unit	Conditions
			Typ Guaranteed Limits				
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V
V _{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I _{OUT} = -50 μA
		3.0 4.5 5.5	- - -	2.56 3.86 4.86	2.46 3.76 4.76	V	$*V_{IN} = V_{IL} \text{ or } V_{IH}$ -12 mA $I_{OH} -24 \text{ mA}$ -24 mA
V _{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	Ι _{ΟUT} = 50 μΑ
		3.0 4.5 5.5	- - -	0.36 0.36 0.36	0.44 0.44 0.44	V	$*V_{IN} = V_{IL} \text{ or } V_{IH}$ 12 mA $I_{OL} \qquad 24 \text{ mA}$ 24 mA
I _{IN}	Maximum Input Leakage Current	5.5	_	±0.1	±1.0	μΑ	V _I = V _{CC} , GND
I _{OZ}	Maximum 3-State Current	5.5	-	±0.5	±5.0	μΑ	$\begin{aligned} &V_{I}\left(OE\right)=V_{IL},V_{IH}\\ &V_{I}=V_{CC},GND\\ &V_{O}=V_{CC},GND \end{aligned}$
I _{OLD}	†Minimum Dynamic Output Current	5.5	-	-	75	mA	V _{OLD} = 1.65 V Max
I _{OHD}		5.5	-	-	-75	mA	V _{OHD} = 3.85 V Min
I _{CC}	Maximum Quiescent Supply Current	5.5	-	8.0	80	μΑ	V _{IN} = V _{CC} or GND

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

*All outputs loaded; thresholds on input associated with output under test.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC} .

[†]Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See AND8277/D at www.onsemi.com)

	Symbol Parameter		74AC				AC		
Symbol			V _{CC} *			T _A = -40°C to +85°C C _L = 50 pF		Unit	Fig. No.
			Min	Тур	Max	Min	Max		
t _{PLH}	Propagation Delay D _n to O _n	3.3 5.0	1.5 1.5	10 7.0	13.5 9.5	1.5 1.5	15 10.5	ns	3–5
t _{PHL}	Propagation Delay D _n to O _n	3.3 5.0	1.5 1.5	9.5 7.0	13 9.5	1.5 1.5	14.5 10.5	ns	3–5
t _{PLH}	Propagation Delay LE to O _n	3.3 5.0	1.5 1.5	10 7.5	13.5 9.5	1.5 1.5	15 10.5	ns	3–6
t _{PHL}	Propagation Delay LE to O _n	3.3 5.0	1.5 1.5	9.5 7.0	12.5 9.5	1.5 1.5	14 10.5	ns	3–6
t _{PZH}	Output Enable Time	3.3 5.0	1.5 1.5	9.0 7.0	11.5 8.5	1.0 1.0	13 9.5	ns	3–7
t _{PZL}	Output Enable Time	3.3 5.0	1.5 1.5	8.5 6.5	11.5 8.5	1.0 1.0	13 9.5	ns	3–8
t _{PHZ}	Output Disable Time	3.3 5.0	1.5 1.5	10 8.0	12.5 11	1.0 1.0	14.5 12.5	ns	3–7
t _{PLZ}	Output Disable Time	3.3 5.0	1.5 1.5	8.0 6.5	11.5 8.5	1.0 1.0	12.5 10	ns	3–8

^{*}Voltage Range 3.3 V is 3.3 V ±0.3 V. Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

			74	AC	74AC		
Symbol	Parameter		T _A = +25°C C _L = 50 pF		T _A = -40°C to +85°C C _L = 50 pF	Unit	Fig. No.
			Тур	Guarant	teed Minimum		
t _s	Setup Time, HIGH or LOW D _n to LE	3.3 5.0	3.5 2.0	5.5 4.0	6.0 4.5	ns	3–9
t _h	Hold Time, HIGH or LOW D _n to LE	3.3 5.0	-3.0 -1.5	1.0 1.0	1.0 1.0	ns	3–9
t _w	LE Pulse Width, HIGH	3.3 5.0	4.0 2.0	5.5 4.0	6.0 4.5	ns	3–6

^{*}Voltage Range 3.3 V is 3.3 V ± 0.3 V. Voltage Range 5.0 V is 5.0 V ± 0.5 V.

DC CHARACTERISTICS

			74	CT	74ACT		
Symbol	Parameter	Parameter V_{CC} $V_A = +25^{\circ}C$		T _A = -40°C to +85°C	Unit	Conditions	
			Typ Guar		ranteed Limits		
V _{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V
V _{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V _{OUT} = 0.1 V or V _{CC} – 0.1 V
V _{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I _{OUT} = -50 μA
		4.5 5.5	- -	3.86 4.86	3.76 4.76	V	$*V_{IN} = V_{IL} \text{ or } V_{IH}$ I_{OH} -24 mA -24 mA
V _{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I _{OUT} = 50 μA
		4.5 5.5	- -	0.36 0.36	0.44 0.44	V	$*V_{IN} = V_{IL} \text{ or } V_{IH}$ 24 mA $I_{OL} \qquad 24 \text{ mA}$
I _{IN}	Maximum Input Leakage Current	5.5	_	±0.1	±1.0	μΑ	V _I = V _{CC} , GND
ΔI_{CCT}	Additional Max. I _{CC} /Input	5.5	0.6	-	1.5	mA	V _I = V _{CC} – 2.1 V
I _{OZ}	Maximum 3-State Current	5.5	-	±0.5	±5.0	μΑ	$\begin{aligned} &V_{I}\left(OE\right) = V_{IL}, V_{IH} \\ &V_{I} = V_{CC}, GND \\ &V_{O} = V_{CC}, GND \end{aligned}$
I _{OLD}	†Minimum Dynamic	5.5	-	-	75	mA	V _{OLD} = 1.65 V Max
I _{OHD}	Output Current	5.5	-	-	-75	mA	V _{OHD} = 3.85 V Min
I _{CC}	Maximum Quiescent Supply Current	5.5	-	8.0	80	μΑ	V _{IN} = V _{CC} or GND

^{*}All outputs loaded; thresholds on input associated with output under test. †Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See AND8277/D at www.onsemi.com)

				74ACT		74	ACT		
Symbol	Parameter	V _{CC} * (V)	T _A = +25°C C _L = 50 pF			T _A = -40°C to +85°C C _L = 50 pF		Unit	Fig. No.
			Min	Тур	Max	Min	Max		
t _{PLH}	Propagation Delay D _n to O _n	5.0	2.5	8.5	10	1.5	11.5	ns	3–5
t _{PHL}	Propagation Delay D _n to O _n	5.0	2.0	8.0	10	1.5	11.5	ns	3–5
t _{PLH}	Propagation Delay LE to O _n	5.0	2.5	8.5	11	2.0	11.5	ns	3–6
t _{PHL}	Propagation Delay LE to O _n	5.0	2.0	8.0	10	1.5	11.5	ns	3–6
t _{PZH}	Output Enable Time	5.0	2.0	8.0	9.5	1.5	10.5	ns	3–7
t _{PZL}	Output Enable Time	5.0	2.0	7.5	9.0	1.5	10.5	ns	3–8
t _{PHZ}	Output Disable Time	5.0	2.5	9.0	11	2.5	12.5	ns	3–7
t _{PLZ}	Output Disable Time	5.0	1.5	7.5	8.5	1.0	10	ns	3–8

^{*}Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS (For Figures and Waveforms – See AND8277/D at www.onsemi.com)

	Parameter			74ACT	74ACT		
Symbol		V _{CC} * (V)	T _A = +25°C C _L = 50 pF		$^{\circ}$ C $T_{A} = -40^{\circ}$ C $to +85^{\circ}$ C $C_{L} = 50 \text{ pF}$		Fig. No.
			Тур	Guarantee	d Minimum		
t _s	Setup Time, HIGH or LOW D _n to LE	5.0	3.0	7.0	8.0	ns	3–9
t _h	Hold Time, HIGH or LOW D _n to LE	5.0	0	0	1.0	ns	3–9
t _w	LE Pulse Width, HIGH	5.0	2.0	7.0	8.0	ns	3–6

^{*}Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C _{IN}	Input Capacitance	4.5	pF	V _{CC} = 5.0 V
C _{PD}	Power Dissipation Capacitance	40	pF	V _{CC} = 5.0 V

ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
MC74AC373DWG	AC373	SOIC-20	38 Units / Rail
MC74AC373DWR2G	AC373	SOIC-20	1000 / Tape & Reel
MC74ACT373DWG	ACT373	SOIC-20	38 Units / Rail
MC74ACT373DWR2G	ACT373	SOIC-20	1000 / Tape & Reel
MC74AC373DTR2G	AC 373	TSSOP-20	2500 / Tape & Reel
MC74ACT373DTR2G	ACT 373	TSSOP-20	2500 / Tape & Reel

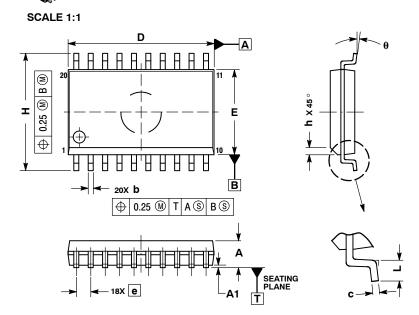
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



DATE 22 APR 2015



- DIMENSIONS ARE IN MILLIMETERS.
 INTERPRET DIMENSIONS AND TOLERANCES.
- PER ASME Y14.5M, 1994.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD
- PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
- DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL

	MILLIMETERS		
DIM	MIN MAX		
Α	2.35	2.65	
A1	0.10	0.25	
b	0.35	0.49	
С	0.23	0.32	
D	12.65	12.95	
E	7.40	7.60	
е	1.27 BSC		
Н	10.05	10.55	
h	0.25	0.75	
L	0.50	0.90	
θ	0°	7 °	

GENERIC MARKING DIAGRAM*

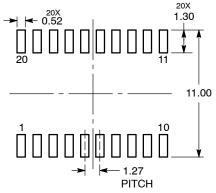


XXXXX = Specific Device Code = Assembly Location

WL = Wafer Lot ΥY = Year WW = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

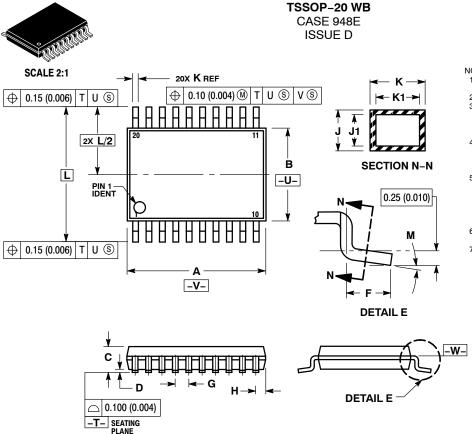
DOCUMENT NUMBER:	98ASB42343B	Electronic versions are uncontrolled except when accessed directly from the Document Repository Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	SOIC-20 WB		PAGE 1 OF 1	

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MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS



DATE 17 FEB 2016

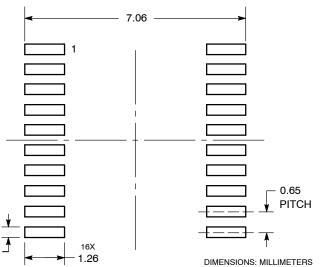
NOTES:

- NOTES:
 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT
- EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.
 INTERLEAD FLASH OR PROTRUSION
- SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

 5. DIMENSION K DOES NOT INCLUDE
 DAMBAR PROTRUSION, ALLOWABLE
 DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K
 DIMENSION AT MAXIMUM MATERIAL CONDITION.
 TERMINAL NUMBERS ARE SHOWN FOR
- 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	6.40	6.60	0.252	0.260
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
Н	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
М	0°	8°	0°	8°

GENERIC RECOMMENDED MARKING DIAGRAM* SOLDERING FOOTPRINT*



	xxxx
	XXXX
	ALYW•
0	-
H	<u> </u>

AAAAAAAAAA

= Assembly Location

= Wafer Lot = Year

= Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present. Some products may not follow the Generic Marking.

*For additional information on our Pb-Free strategy and soldering
details, please download the onsemi Soldering and Mounting
Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	TSSOP-20 WB		PAGE 1 OF 1	

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